

**HAI LECK HOLDINGS LIMITED**  
(Incorporated in the Republic of Singapore)  
(Company Registration Number: 199804461D)

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**PROPOSED BONUS ISSUE – APPROVAL IN PRINCIPLE FOR LISTING AND QUOTATION**

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The board of directors (the “**Board**”) of Hai Leck Holdings Limited (the “**Company**”) refers to the Company’s announcement on 14 May 2021 in relation to the Proposed Bonus Issue (the “**Announcement**”). Unless otherwise defined herein or the context otherwise requires, all capitalised terms used in this announcement shall bear the meanings ascribed to them in the Announcement.

Further to the Announcement, the Board is pleased to inform that the Company has on 28 May 2021 received the approval-in-principle of the SGX-ST for the listing and quotation of up to 20,599,394 Bonus Shares on the Mainboard of the SGX-ST, subject to the following:

- (a) compliance with the SGX-ST’s listing requirements; and
- (b) submission of a written confirmation that the Proposed Bonus Issue is in compliance with the relevant Companies Act.

The in-principle approval of the SGX-ST is not to be taken as an indication of the merits of the Proposed Bonus Issue, the Bonus Shares, the Company and/or its subsidiaries. The Company will announce the details of the Record Date for the purpose of determining Shareholders’ entitlements to the Bonus Shares in due course.

BY ORDER OF THE BOARD

Cheng Buck Poh  
Executive Chairman and Chief Executive Officer

31 May 2021